

JOC851 Series

Rev.A.1.0

DESCRIPTION:

The JOC851 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar high voltage phototransistor detector in a plastic DIP4 package with different lead forming options. With the robust coplanar double mold structure, JOC851 series provide the most stable isolation feature. The products are widely used in switch modepower supplies, programmable controllers, household appliances and office equipment.

MAIN FEATURES

Current transfer ratio (CTR: 50%-600% @ $I_F=5mA$, $V_{CE}=5V$)

High isolation voltage between input and output

($V_{iso}=5,000V_{rms}$)

Operating temperature up to +110°C

Collector-Emitter voltage $BV_{CEO} \geq 350V$

CQC approved

VDE approved

UL approved

RoHS & REACH Compliance



ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	60	mA
	Peak Forward Current	I_{FP}	1 ^①	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	100	mW
Output	Collector-emitter Voltage	V_{CEO}	350	V
	Emitter-collector Voltage	V_{ECO}	7	V
	Collector Current	I_C	50	mA
	Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	200	mW
Isolation Voltage		V_{iso}	5000 ^②	Vrms
Operating Temperature		T_{opr}	-55~+110	°C

Storage Temperature	T_{stg}	-55~+125	°C
Soldering Temperature	T_{sol}	260	°C

NOTE1: 100μs pulse, 100Hz frequency

NOTE2: AC for 1minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10mA$	-	1.24	1.4	V
			$I_F=20mA$	-	1.3	1.5	
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA
	Terminal Capacitance	C_t	$V=0$, $f=1MHz$	-	30	250	pF
Output	Collector-Emitter dark current	I_{CEO}	$V_{CE}=200V$, $I_F=0$	-	-	100	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	$I_C=0.1mA$ $I_F=0$	350	-	-	V
	Emitter-Collector breakdown voltage	BV_{ECO}	$I_E=0.1mA$ $I_F=0$	7	-	-	V
Transfer Characteristics	Current transfer ratio	$CTR^{①}$	$I_F=5mA$ $V_{CE}=5V$	50	-	600	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F=20mA$ $I_C=1mA$	-	0.06	0.2	V
	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	5×10^{10}	10^{11}	-	Ω
	Floating Capacitance	C_{IO}	$V=0$, $f=1MHz$	-	0.6	1	pF
	Cut-off Frequency	f_c	$V_{CE}=5V$, $I_C=2mA$ $R_L=100\Omega$, -3dB	-	80	-	kHz
	Rise Time	t_r	$V_{CE}=2V$, $I_C=2mA$ $R_L=100\Omega$	-	3	18	μs
	Fall Time	t_f		-	4	18	μs
	Response Time	t_{on}		-	5	25	μs
		t_{off}		-	4	25	μs

ORDERING AND MARKING INFORMATION

MARKING INFORMATION			
		JOC : Company Abbr. 851 : Part Number V : VDE Option Y : Fiscal Year A : Manufacturing Code WW : Work Week	
ORDERING INFORMATION			
JOC851(Y)(Z)-GV			
JOC – Company Abbr. 851 – Part Number Y – Lead Form Option (M/S/SL/SLM/None) Z – Tape and Reel Option (T1/T2/T3/T4) G – Green V – VDE Option (V or None)			
Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
None/M	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box =32k Units
S(T1/T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =22.5k Units
S(T3/T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units
SL(T1/T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =22.5k Units
SL(T3/T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units
SLM(T1/T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =22.5k Units

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

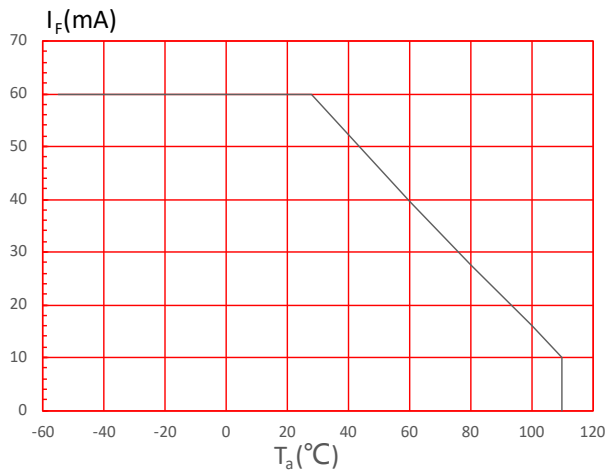


FIG.2: Collector Power Dissipation vs. Ambient Temperature

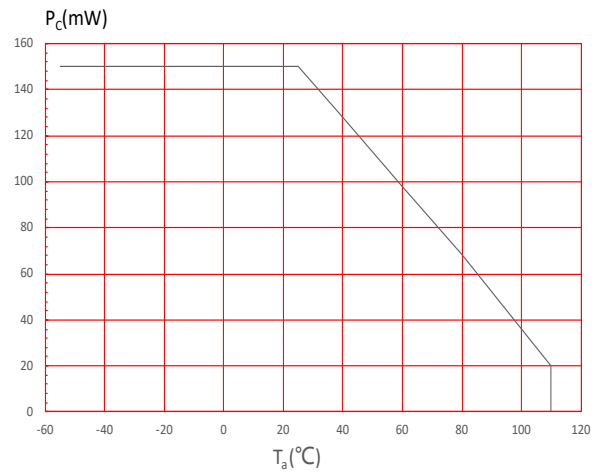


FIG.3: Forward Current vs. Forward Voltage

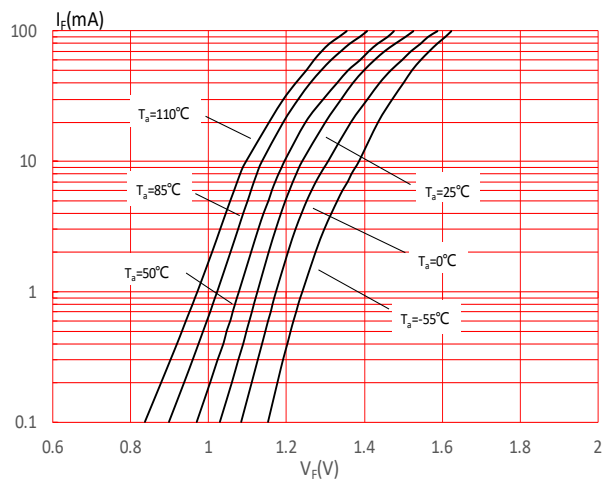


FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

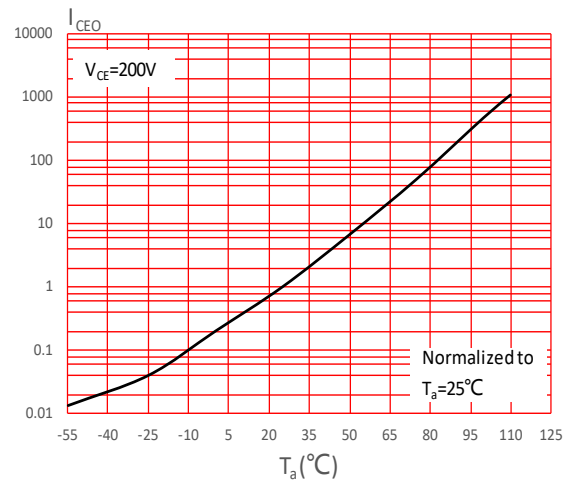


FIG.5: Collector Current vs. Collector-emitter Voltage

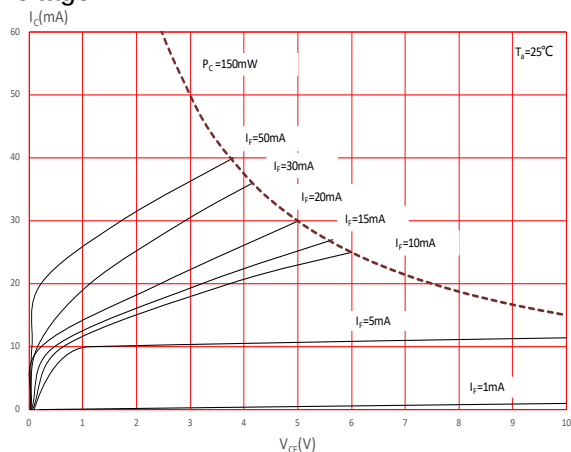


FIG.6: Normalized Current Transfer Ratio vs. Forward Current

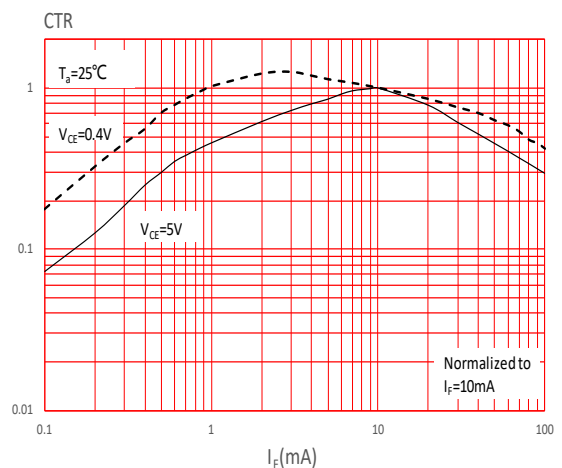
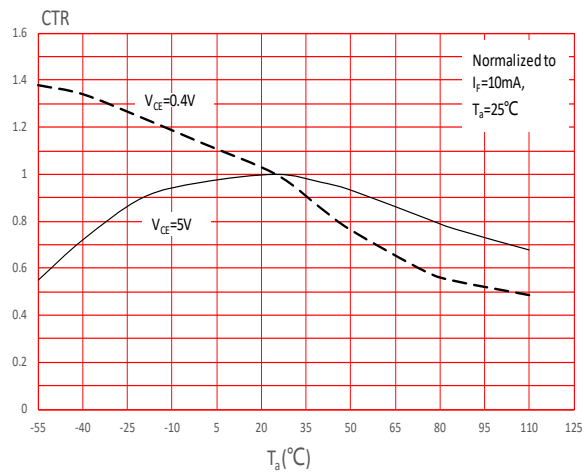
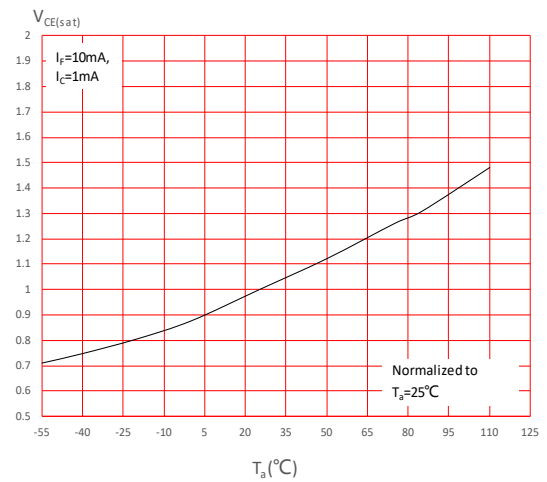
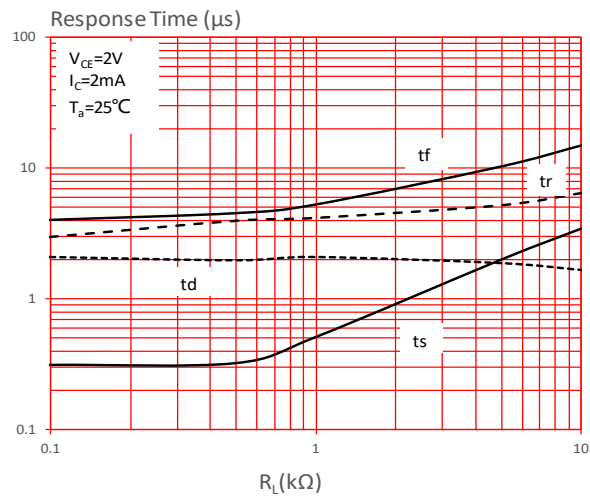
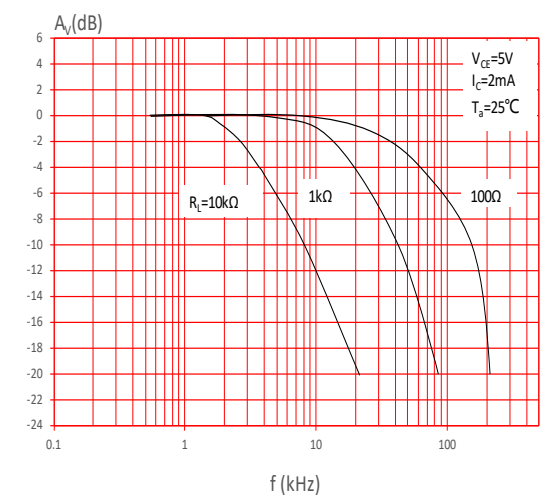
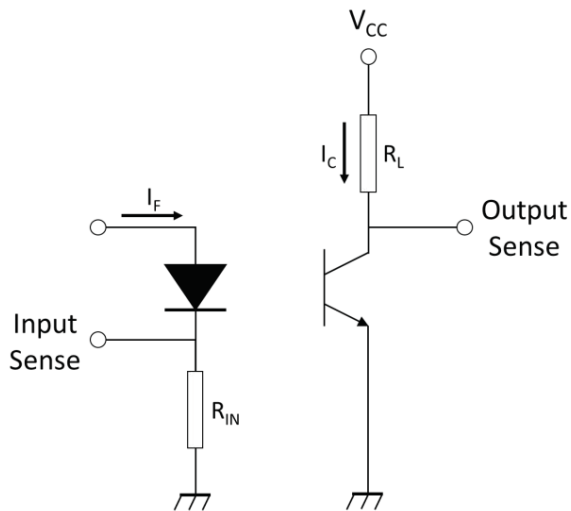
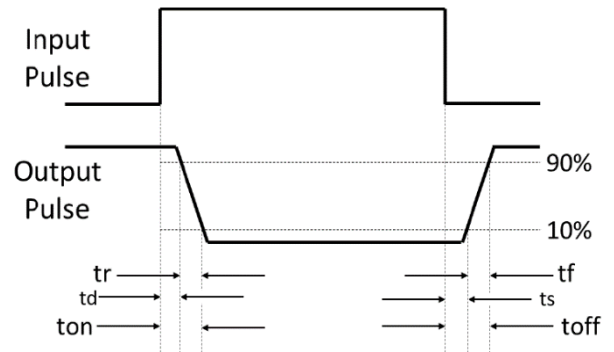
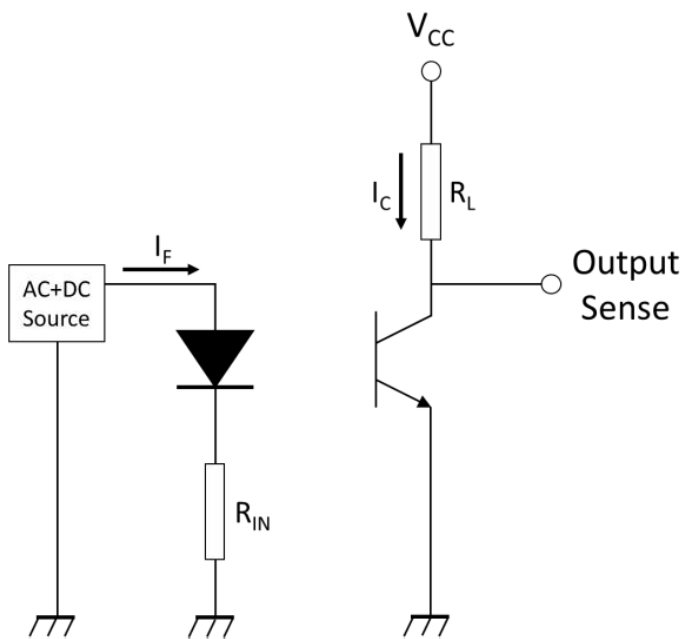


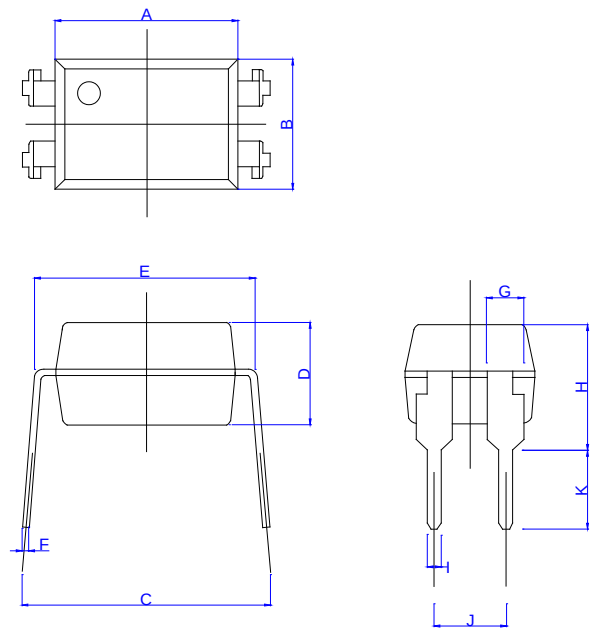
FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

FIG.9: Response Time vs. Load Resistance

FIG.10: Frequency Response


Test Circuits

FIG.11: Test Circuits of Response Time

FIG.12: Curves of Response Time

FIG.13: Test Circuits of Frequency Response


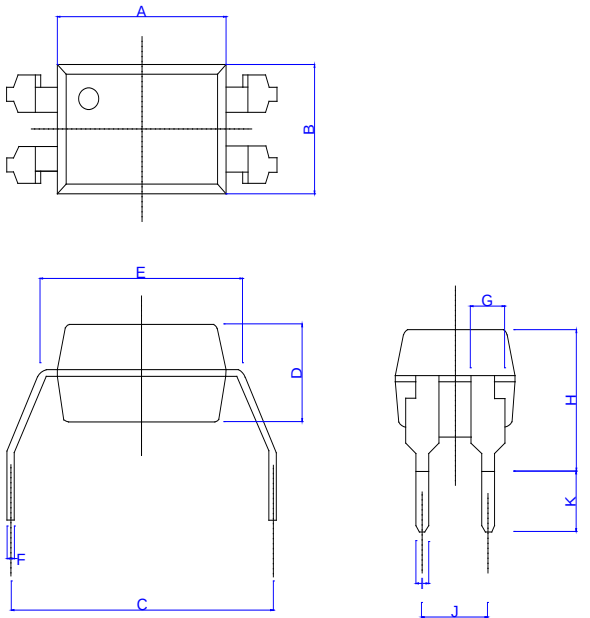
Package Dimension (Unit: mm)

Standard DIP Type:



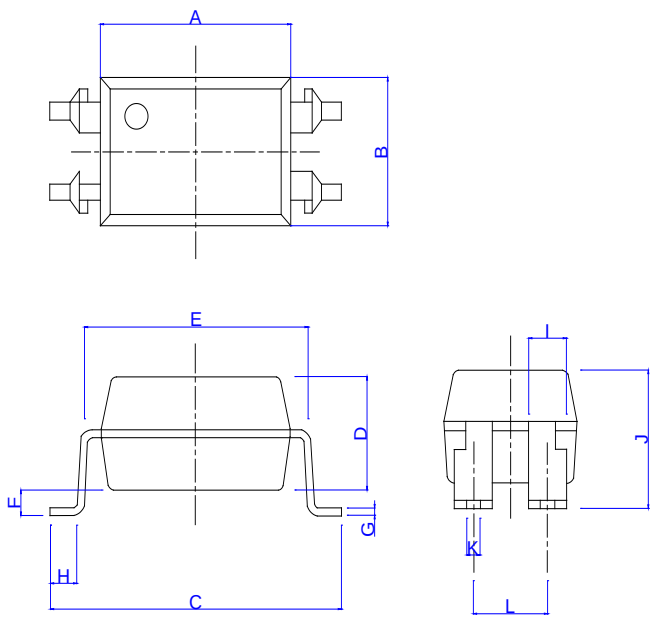
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.236		0.276
B	4.08		5.08	0.161		0.200
C	7.62		10.16	0.300		0.400
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.15		0.36	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.50		4.80	0.138		0.189
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.45		3.50	0.096		0.138

Option M Type:



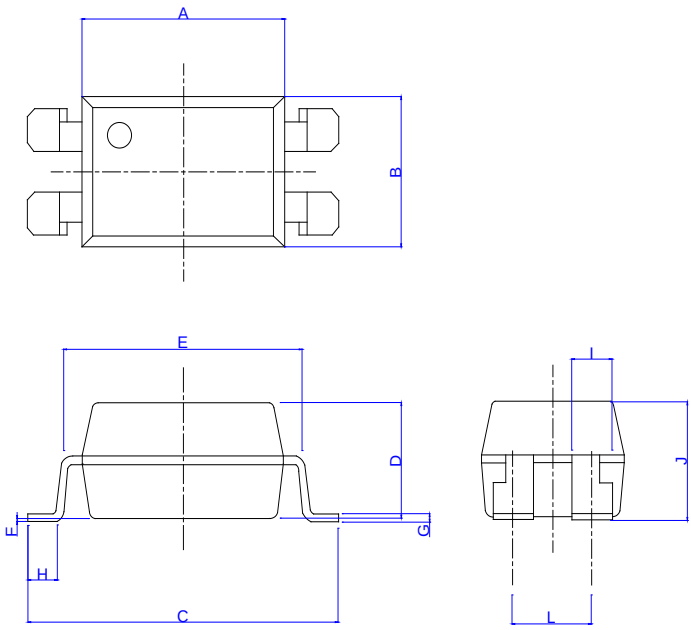
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.244		0.268
B	4.10		4.90	0.161		0.193
C	9.66		10.66	0.380		0.420
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.15		0.36	0.006		0.014
G	0.90		1.50	0.036		0.059
H	4.16		4.88	0.164		0.192
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.00		2.70	0.079		0.106

Option S Type:



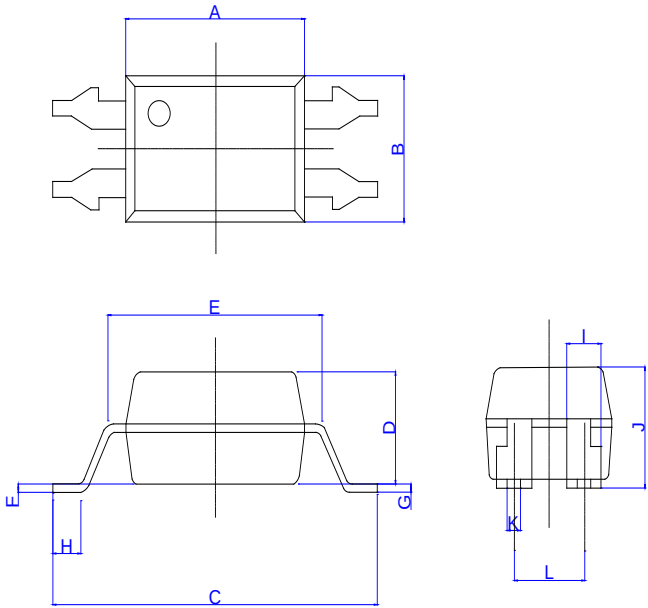
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.244		0.268
B	4.30		4.90	0.169		0.193
C	9.86		10.50	0.388		0.413
D	3.20		3.80	0.126		0.150
E	7.32		7.92	0.288		0.312
F	0.00		1.00	0.000		0.039
G	0.15		0.35	0.006		0.014
H	0.50		1.10	0.020		0.043
I	1.10		1.50	0.043		0.059
J	3.50		4.80	0.138		0.189
K	0.40		0.60	0.016		0.024
L	2.29		2.79	0.090		0.110

Option SL Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.236		0.276
B	4.08		5.08	0.161		0.200
C	9.50		10.50	0.374		0.413
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.00		0.60	0.000		0.024
G	0.15		0.36	0.006		0.014
H	0.50		1.40	0.020		0.055
I	0.90		1.50	0.035		0.059
J	3.20		4.35	0.126		0.171
L	2.29		2.79	0.090		0.110

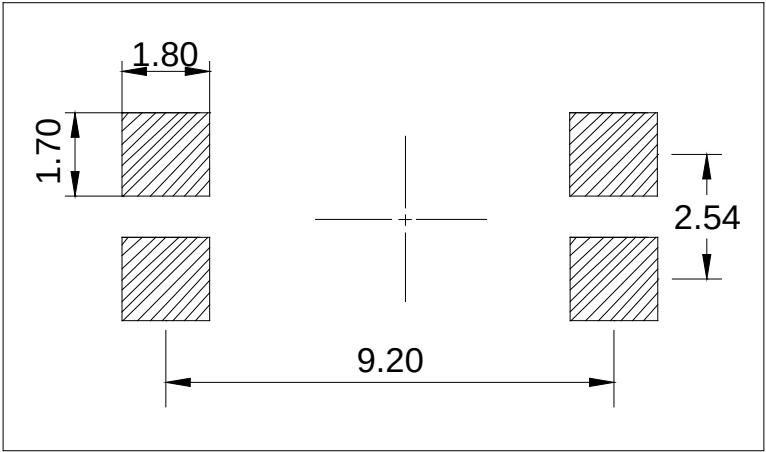
Option SLM Type:



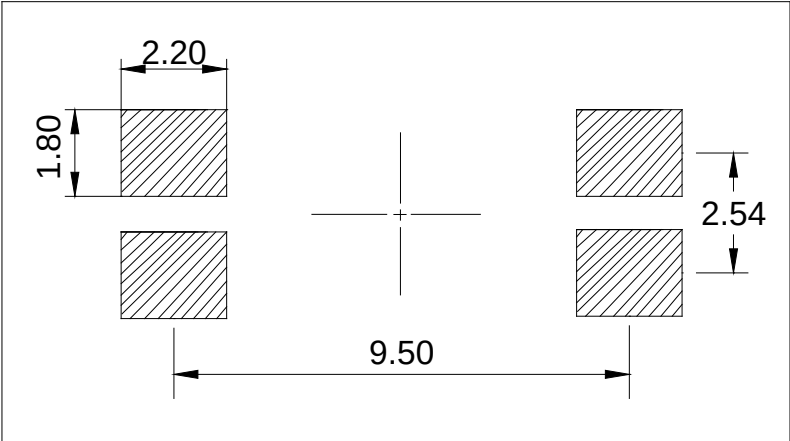
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.248		0.264
B	4.38		4.78	0.172		0.188
C	11.60		12.10	0.457		0.476
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F	0.00		0.30	0.000		0.012
G	0.20		0.30	0.008		0.012
H	0.50		0.90	0.020		0.035
I	1.15		1.35	0.045		0.053
J	3.45		3.85	0.136		0.152
K	0.45		0.55	0.018		0.022
L	2.34		2.74	0.092		0.108

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

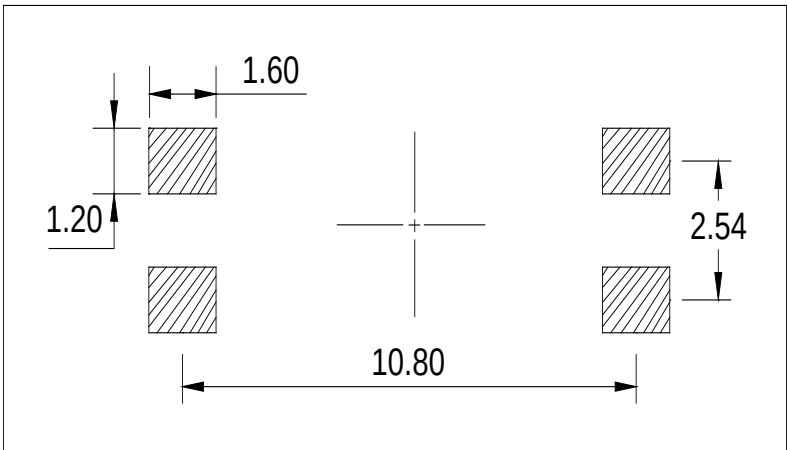
Option S



Option SL

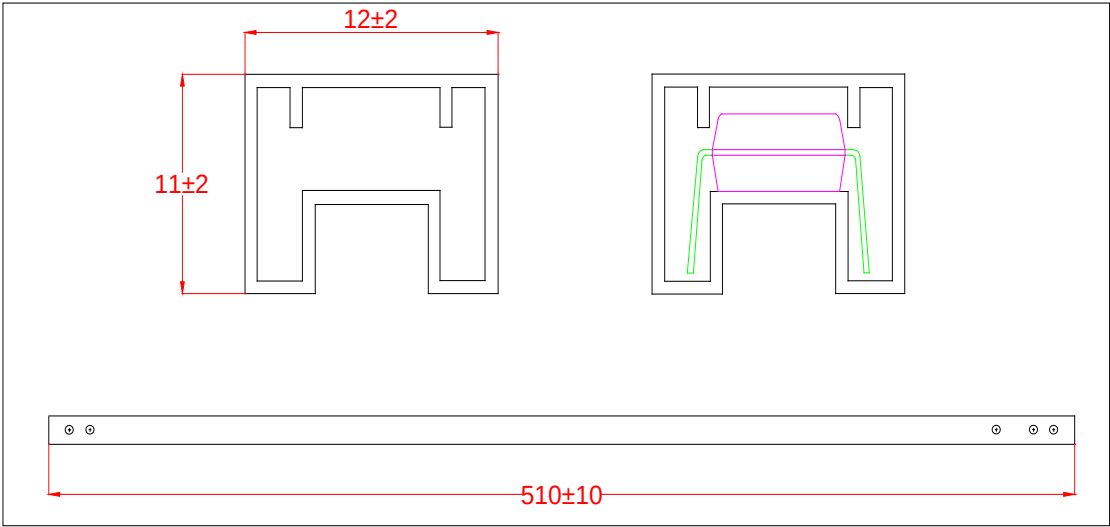


Option SLM

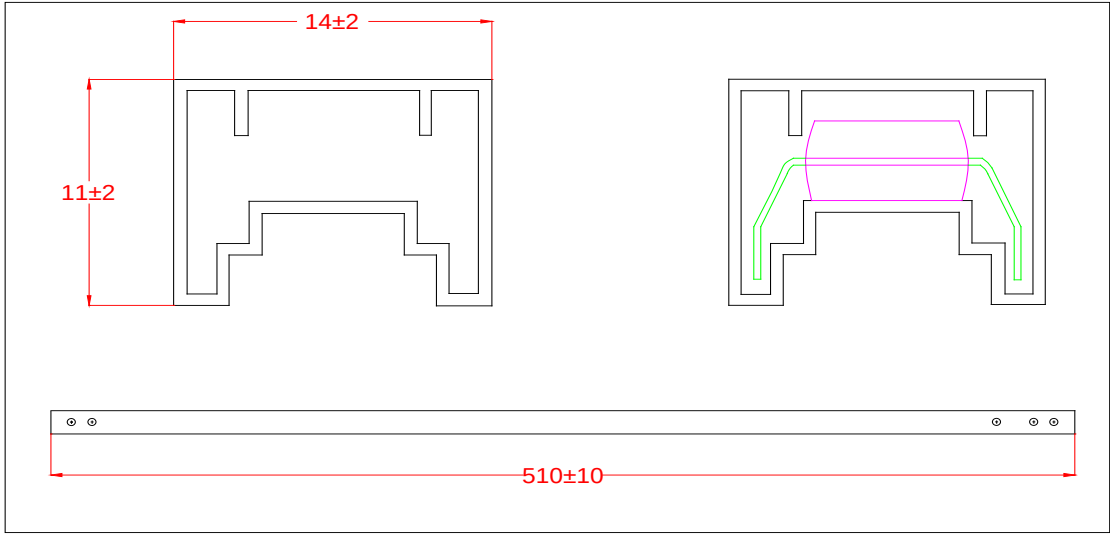


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP

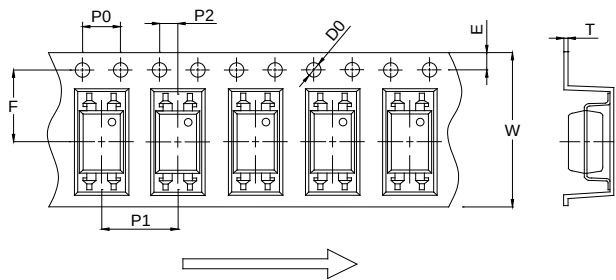


Option M



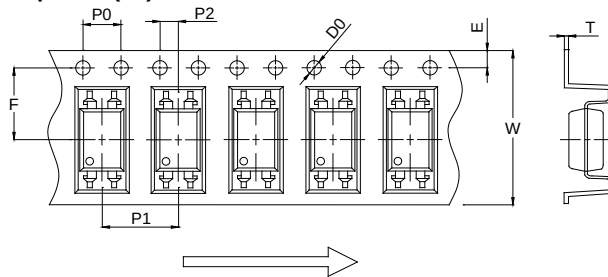
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T1)

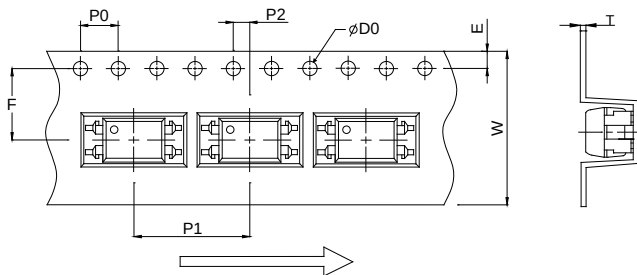


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.65		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.30	0.40	0.50	0.012	0.016	0.020
W	15.70	16.00	16.30	0.618	0.630	0.642

Option S(T2)

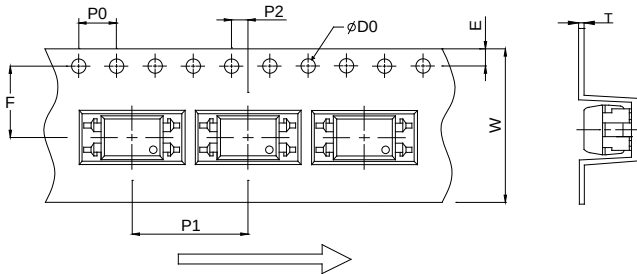


Option S(T3)

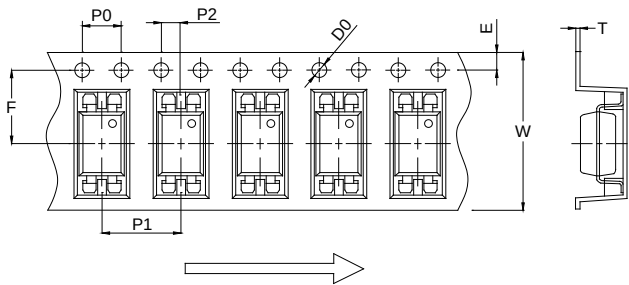


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.65		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.30	0.40	0.50	0.012	0.016	0.020
W	15.70	16.00	16.30	0.618	0.630	0.642

Option S(T4)

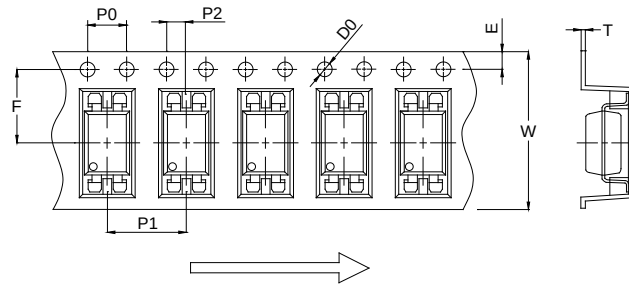


Option SL(T1)

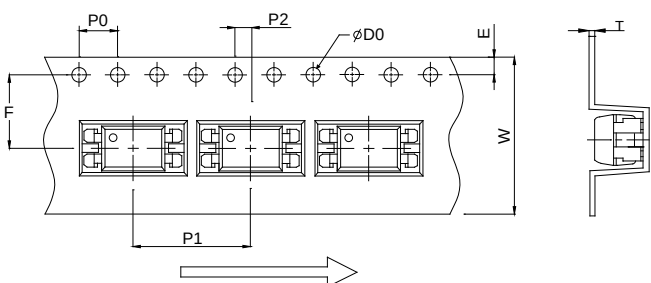


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

Option SL(T2)

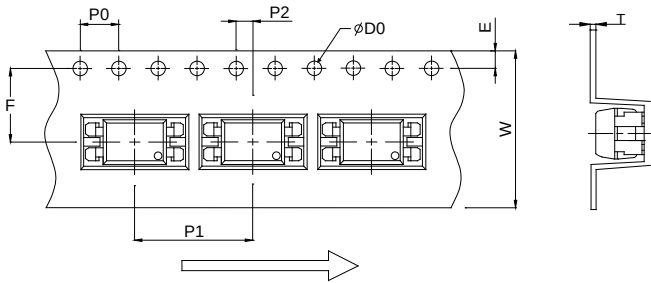


Option SL(T3)

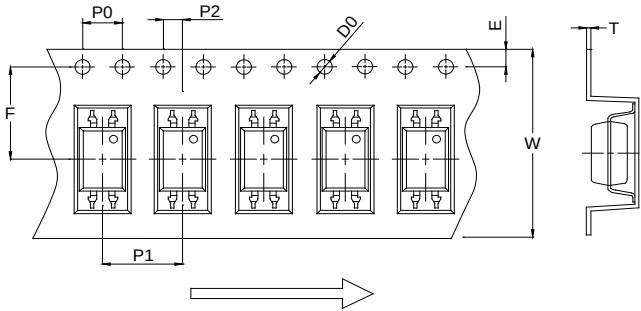


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.45	0.55	0.014	0.018	0.022
W	15.70	16.00	16.30	0.618	0.630	0.642

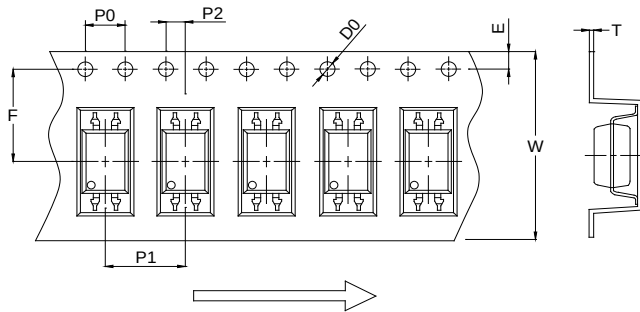
Option SL(T4)



Option SLM(T1)

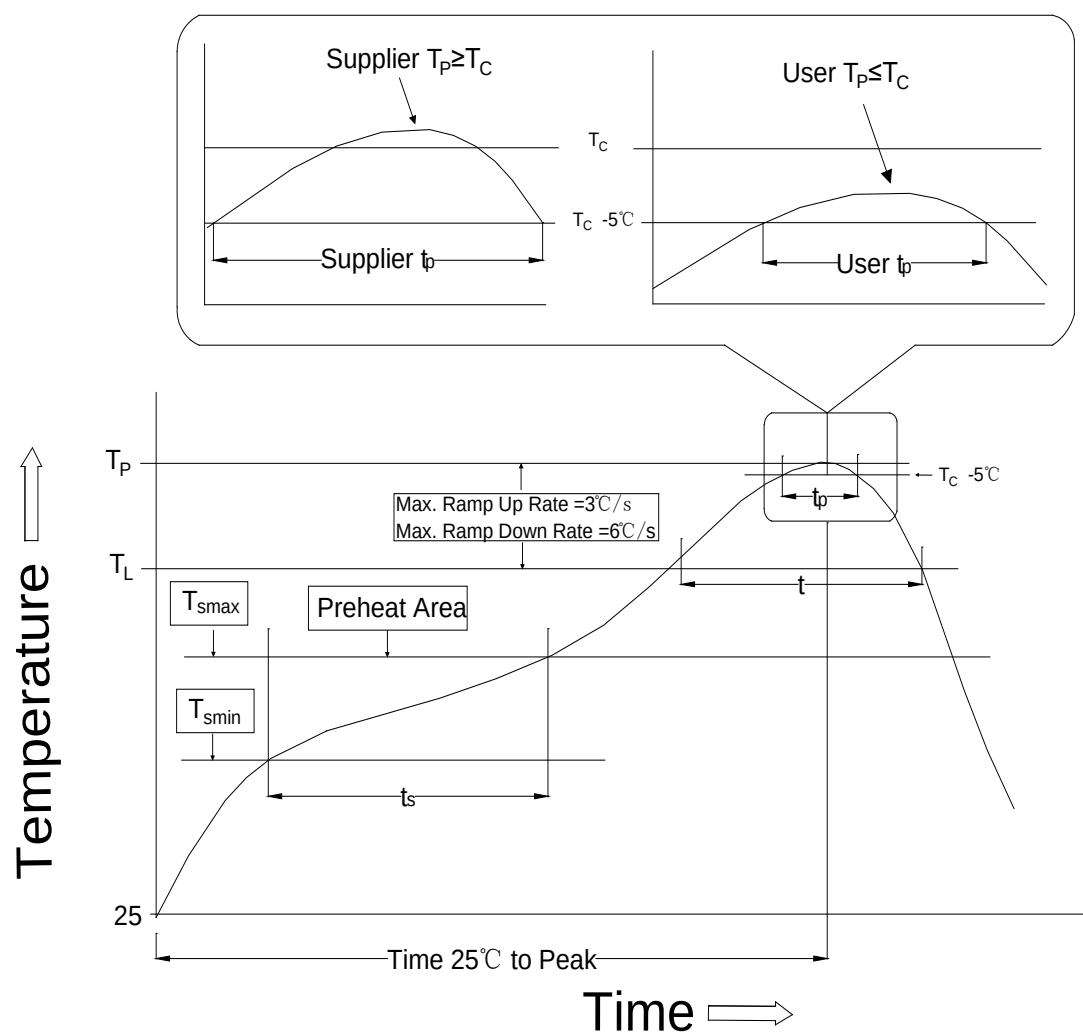


Option SLM(T2)



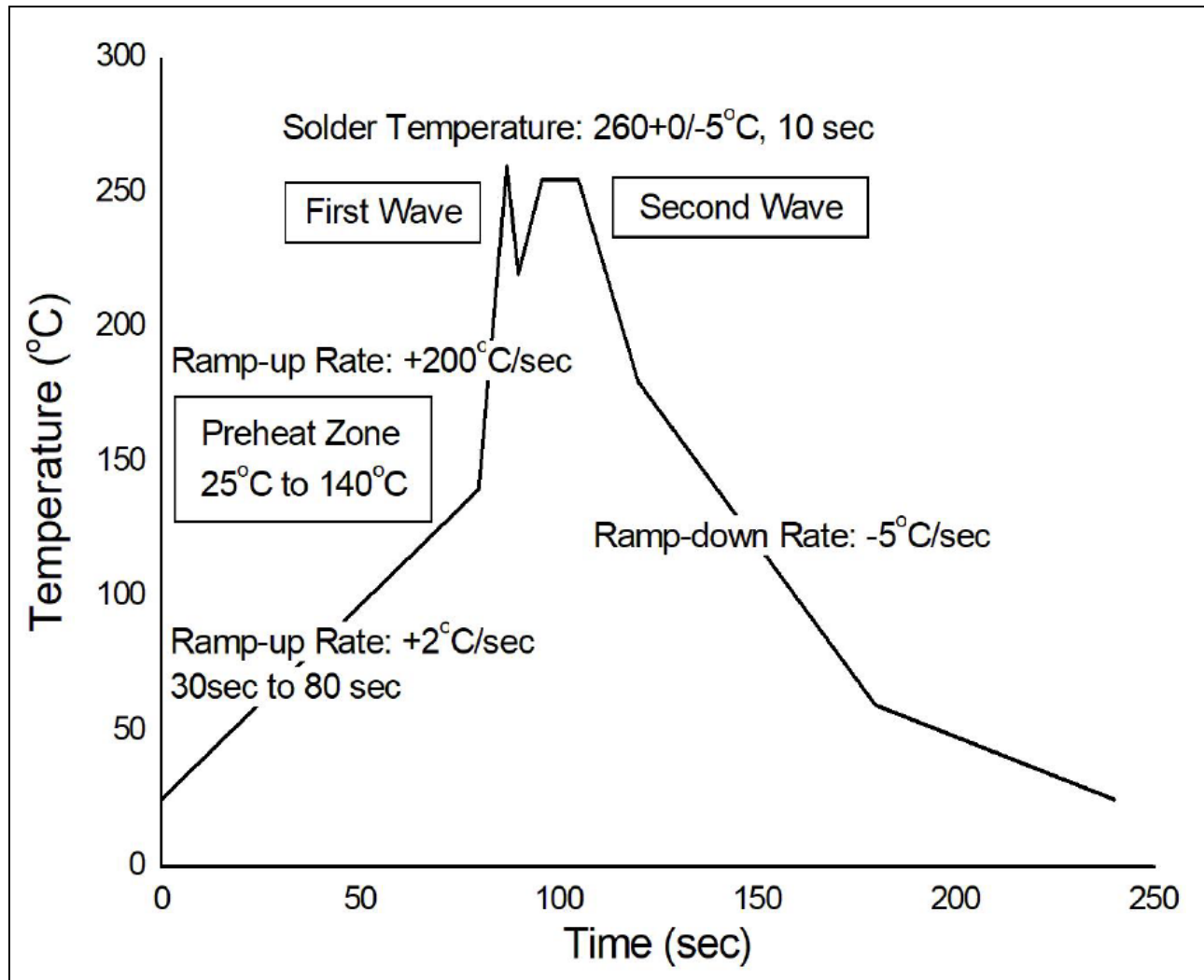
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	11.45	11.50	11.55	0.451	0.453	0.455
T	0.35	0.40	0.45	0.014	0.016	0.018
W	23.70	24.00	24.30	0.933	0.945	0.957

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	100	150°C
Temperature Max. (T_{smax})	150	200°C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.	3°C/second max.
Liquidus Temperature (T_L)	183°C	217°C
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t_P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	$360 \pm 5^{\circ}\text{C}$
Soldering Time	3s max.

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